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(54) THERMAL TRANSFER STRUCTURES FOR IMMERSION COOLING

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ABSTRACT (57)

A thermal management device is described. The device includes a substrate having a spreader surface and a plurality of thermal features connected to the spreader surface of the substrate. At least one thermal feature includes a body having a longitudinal axis and a hollow bore having an inner diameter perpendicular to the longitudinal axis and an opening at a distal end distal from the substrate.

